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PRE-STANDARD



**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 3-913: Test methods for interconnection structures (printed boards) –
Electronic circuit board for high-brightness LEDs**

INTERNATIONAL
ELECTROTECHNICAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 3-913: Test methods for interconnection structures (printed boards) –
Electronic circuit board for high-brightness LEDs**

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 3-913: Test methods for interconnection structures (printed boards) – Electronic circuit board for high-brightness LEDs

1 Scope

This standard specifies the test methods of the electronic circuit board for high-brightness LEDs (hereafter described as electronic circuit board).

NOTE Reference documents to this standard are listed in Clause 11 Normative references and in the Bibliography.